# **MA3X157A** (MA157A)

## Silicon epitaxial planar type

#### For switching circuits

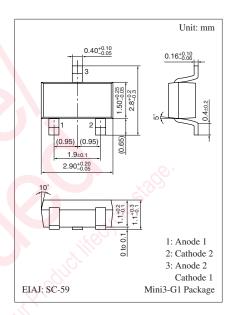
#### ■ Features

- High switching speed
- Small terminal capacitance C<sub>t</sub>
- Both chips have even characteristics

### ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

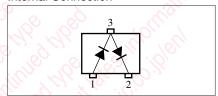
Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	80	V
Maximum peak reverse voltage		V <sub>RM</sub>	80	V
Forward current	Single	$I_{F}$	100	mA
	Series		65	
Peak forward	Single	$I_{FM}$	225	mA
current	Series		145	٠,
Non-repetitive peak	Single	$I_{FSM}$	500	mA
forward surge current*	Series		325	40/10
Junction temperature		T <sub>j</sub>	150	G°C √C
Storage temperature		T <sub>stg</sub>	-55 to +150	°C

Note) \*: t = 1 s



Marking Symbol: MS

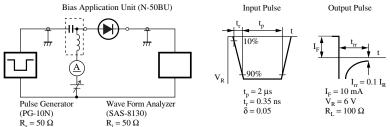
#### Internal Connection



### ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

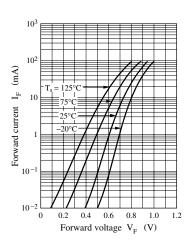
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$	0.7		1.2	V
Reverse voltage	$V_R$	$I_R = 100 \mu A$	80			V
Reverse current	$I_R$	V <sub>R</sub> = 75 V			100	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$			2	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
Mis		$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

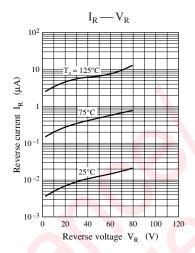
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. Absolute frequency of input and output is 100 MHz.
  - 3. \*: t<sub>rr</sub> measurement circuit

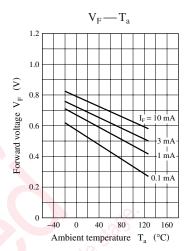


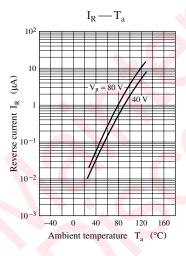
Note) The part number in the parenthesis shows conventional part number.

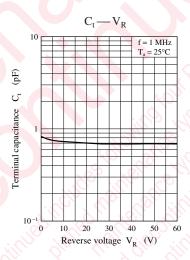
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